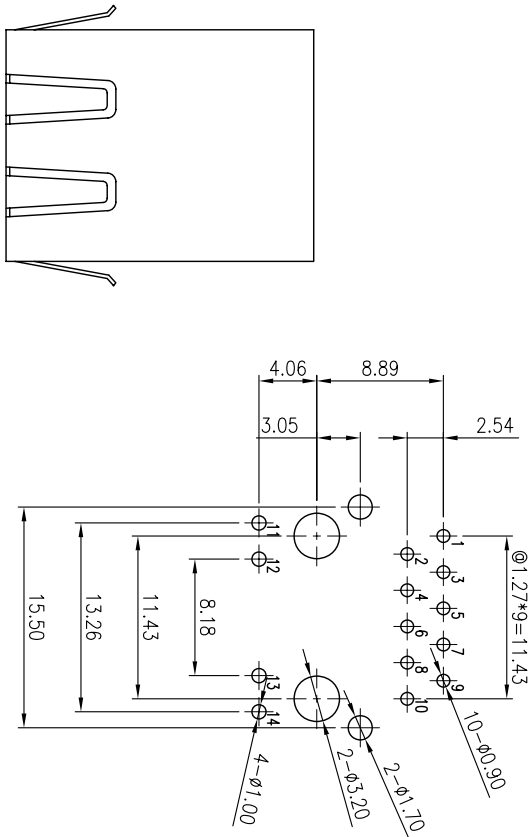
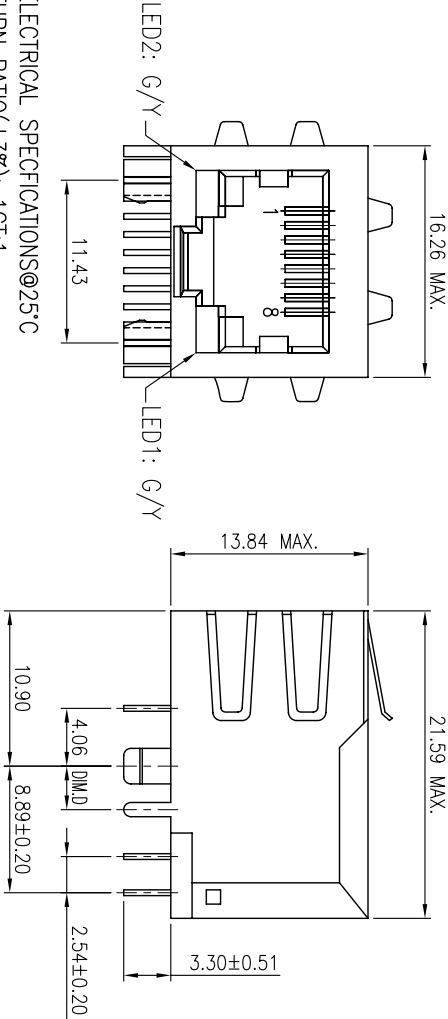
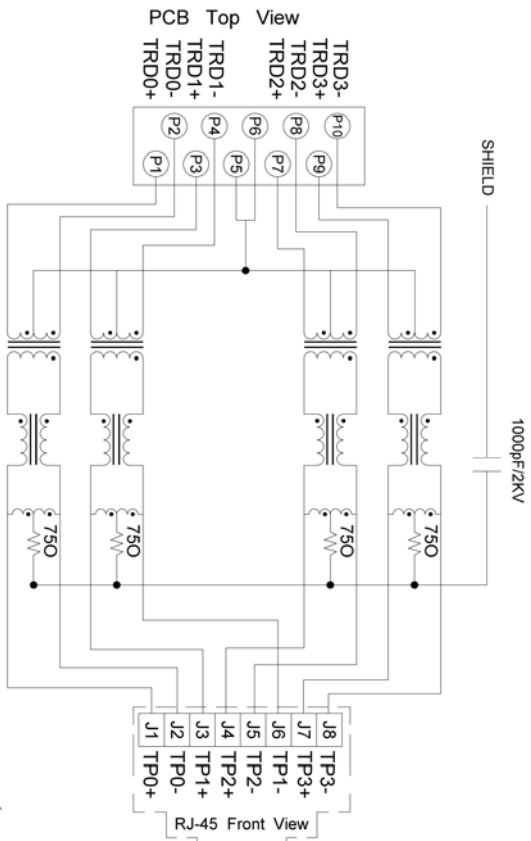




PC BOARD LAYOUT
COMPONENT SIDE SHOWN



ORDER INFORMATION:
MUKf4803-Po80GXSb-D-L8P
MUKf: MODULAR JACK WITH FILTER
4803: SERIES NO.
Po: PCB TYPE, RIGHT ANGLE
80: 8P10C
GX: CONTACT PLATING OPTION
Gf: GOLD FLASH ON CONTACT & SOLDER TAIL
Gft: GOLD FLASH ON CONTACT, TIN PLATED ON SOLDER TAIL
G15t: 15u" GOLD ON CONTACT, TIN PLATED ON SOLDER TAIL
G30t: 30u" GOLD ON CONTACT, TIN PLATED ON SOLDER TAIL
G50t: 50u" GOLD ON CONTACT, TIN PLATED ON SOLDER TAIL
Sb: SHIELDED WITH PANEL GROUNDING TAB
D: DIM D= 3.05mm, PLASTIC PEG IN THE FRONT
L8: LED1: BI-COLOR G/Y; LED2: BI-COLOR G/Y
P: LED PINS ARE PARALLEL

ELECTRICAL SPECIFICATIONS@25°C
TURN RATIO(±3%): 1CT:1
OCL(100KHz/0.1V@8mA): 350uH MIN.
INSERTION LOSS(dB TYP.): -0.8dB(0.3-100MHz), -1.2dB(100-120MHz)
RETURN LOSS(dB MIN.): -18dB(0.5-40MHz), -12+20log(f/80MHz)dB(40-100MHz)
CROSS TALK(dB TYP.): -33+20log(f/100MHz)dB(0.3-100MHz)
CMR(dB MIN.): -30dB(0.3-100MHz)
CDMR(dB TYP.): -35dB(0.3-100MHz)
DCR: 1.0Ω MAX.
HI-POT TEST: 1500Vrms/0.5mA/60Sec OR 1650Vrms/0.5mA/2Sec
OPERATING TEMPERATURE: 0°C TO +70°C

TOLERANCES UNLESS OTHERWISE SPECIFIED		SIGNATURES		DATE		TITLE		MODEL	
SYMBOL	UNIT	SCALE	DRAWN	KEN	24/SEP/08	CHECKED	WENDY	24/SEP/08	NO.
△	mm	2/1	APPROVALS						MUKf4803-Po80G_Sb-D-L8P

MMT CORPORATION